

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current
11	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6108901 A	20000829	7	Tool for implementing non-destructive separation	29/842	29/762; 29/764
12	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5502887 A	19960402	10	Chip extraction tool	29/764	29/758
13	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5219378 A	19930615	8	Reciprocating cutting tool and method	30/169	156/584; 30/337
14	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 4756078 A	19880712	7	Integrated circuit package extraction tool	29/764	29/268
15	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5278393 A	19940111	4	Electrically heated desoldering unit having	219/228	219/221; 219/230;
16	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5281165 A	19940125	10	Electrical connector shroud adapted for shorting bar	439/510	439/189; 439/79;
17	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 4034202 A	19770705	8	Integrated circuit pack extractor	219/230	219/533; 228/19;
18	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6249960 B1	20010626	8	Tool for manipulating an electrical connector and	29/762	29/750; 29/758;
19	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5440803 A	19950815	7	Integrated circuit extraction tool	29/764	254/120; 254/131;
20	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 4961256 A	19901009	6	Extraction tool	29/764	29/267
21	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 3443297 A	19690513	4	CIRCUIT MODULE EXTRACTOR	29/764	29/239
22	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 4896019 A	19900123	7	Electric soldering iron for simultaneously soldering or	219/228	219/238; 219/243;
23	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6259155 B1	20010710	6	Polymer enhanced column grid array	257/690	257/693; 257/778;
24	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6111220 A	20000829	11	Circuit and method for heating an adhesive to	219/209	174/52.1 257/704;
25	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 4771932 A	19880920	6	Method for soldering and desoldering electronic	228/180.1	228/264

US 20030159280A1	20030828	Method of removing optical device	29/840	Young, Craig A. et al.
US 6646777 B2	20031111	Optical isolator with improved mounting characteristics	359/281	Qin, Wenhong et al.
US 5116015 A	19920526	Security mounting	248/553	Gassaway, Mark M.
US 6221199 B1	20010424	Apparatus and method for removing an adhesive bonded pad	156/344	Chang, Yu-Chia et al.
US 6629363 B1	20031007	Process for mechanically attaching a temporary lid to a microelectronic package	29/832	Chan, Joseph Ying-Yuen
US 6136128 A	20001024	Method of making an adhesive preform lid for electronic devices	156/235	Chung, Kevin Kwong-Tai
US 4931806 A	19900605	Window mounted antenna for a cellular mobile telephone	343/715	Wunderlich, Blake A.
US 6111357 A	20000829	Organic electroluminescent display panel having a cover with radiation-cured perimeter seal	313/509	Fleming, Paul J. et al.
US 5448814 A	19950912	Hand tool for removal of adhesively mounted items, particularly cellular telephone antennas	29/239	Fisher, Roger K.
US 4349993 A	19820921	Molding clip assemblage	52/208	Tanaka, Toshie et al.
US 3744758 A	19730710	LEVER AND FULCRUM COMBINATION	254/129	Nakasone, Harold Y.
US 5502887 A	19960402	Chip extraction tool	29/764	Gonzales, Guadalupe V.
US 5219378 A	19930615	Reciprocating cutting tool and method	30/169	Arnold, Robert A.
US 3986265 A	19761019	Orthodontic tool for removing epoxy secured brackets and epoxy residue	433/4	Cusato, Anthony J.
US 6108901 A	20000829	Tool for implementing non-destructive separation of electrical components	29/842	Kossor, Michael G.
US 4756078 A	19880712	Integrated circuit package extraction tool	29/764	Dougherty, Michael J. et al.
US 6178097 B1	20010123	RF shield having removable cover	361/816	Hauk, Jr., Karel
US 5726859 A	19980310	Circuit board component retainer and extractor	361/760	Khadem, Gita et al.
US 4034202 A	19770705	Integrated circuit pack extractor	219/230	Vandermark, Harold F.
US 3980861 A	19760914	Electrically heated miniature thermal implement	219/230	Fukunaga, Akio
US 3785033 A	19740115	DUAL INLINE PACKAGE HANDLING TOOL	29/764	Lynch, Leonard J.
US 6029341 A	20000229	Latch tool for electrical connector	29/747	Self, Jr., Daines Milfred
US 5367761 A	19941129	Printed circuit board assembly extractor tool	29/764	Kabat, Zbigniew et al.
US 6249960 B1	20010626	Tool for manipulating an electrical connector and method of use	29/762	Faesel, Dennis W.
US 5469614 A	19951128	Electrical outlet cover remover	29/764	Lyonnais, Debra
US 4961256 A	19901009	Extraction tool	29/764	Faillace, Nicholas J.
US 4389770 A	19830628	Tri-lead cable housing removal tool	29/764	Bocinski, Terrance E. et al.
US 3443297 A	19690513	CIRCUIT MODULE EXTRACTOR	29/764	LUSBY THOMAS K JR
US 5440803 A	19950815	Integrated circuit extraction tool	29/764	Selgas, Jr., Thomas D. et al.
US 3990863 A	19761109	Integrated-circuit block extraction tool	29/764	Palmer, Harold D.
US 5281165 A	19940125	Electrical connector shroud adapted for shorting bar removal	439/510	McCleerey, Earl W. et al.
US 5278393 A	19940111	Electrically heated desoldering unit having adjustable stop means preventing circuit board damage	219/228	Kim, Henry
US 4896019 A	19900123	Electric soldering iron for simultaneously soldering or desoldering a row of integrated circuit leads	219/228	Hyun, Kim T.

L Number	Hits	Search Text	DB	Time stamp
1	1502	remov\$4 same optical adj device	USPAT; EPO; JPO	2004/03/05 10:45
2	5	(remov\$4 same optical adj device) and	USPAT; EPO; JPO	2004/03/05 10:45
3	138	(pry prying) same adhesive (repair\$4 replac\$3 rework\$3) and (prying pry detach\$3 extract\$3) same (adhesive solder) same (board substrate) same (lead pin wire)	USPAT; EPO; JPO	2004/03/05 13:53
5	392	(repair\$4 replac\$3 rework\$3) and (prying pry extract\$3) and insert\$3 and (peel\$4 remov\$3) and (adhesive solder) same (board substrate) same (lead pin wire)	USPAT; EPO; JPO	2004/03/05 14:11
6	2	(repair\$4 replac\$3 rework\$3).ti. and (prying pry) and (peel\$4 remov\$3) and (adhesive solder) and (board substrate) and (lead pin wire) and tool	USPAT; EPO; JPO	2004/03/05 14:12
7	6	(repair\$4 replac\$3 rework\$3) and (prying pry) and (peel\$4 remov\$3) and (adhesive solder) and (board substrate) and (lead pin wire) and tool.ti.	USPAT; EPO; JPO	2004/03/05 14:13
8	116	(repair\$4 replac\$3 rework\$3) and (prying pry) and (peel\$4 remov\$3) and (adhesive solder) and (board substrate) and (lead pin wire) and tool	USPAT; EPO; JPO	2004/03/05 14:14
-	16	craig.in. and optical adj device.ti.	USPAT; EPO; JPO	2004/02/20 18:57
-	24	craig.in. and optical adj device.ti.	USPAT; US-PGPUB; EPO; JPO	2004/02/20 18:57
-	11	29/832,840,426.1,426.5,762,764.ccls. and adhesive adj pad	USPAT; EPO; JPO	2004/03/03 14:37
-	3	peel\$4 same adhesive adj pad and optical adj device	USPAT; EPO; JPO	2004/03/03 14:57
-	22	("4740977"   "4770505"   "4818881"   "4909612"   "4942076"   "5055652"   "5105307"   "5479540"   "5542018"   "5638391"   "5712728"   "5715080"   "5978135"   "6055102"   "6081638"   "6146025"   "6205274"   "6215295"   "6219470"   "6301279"   "6441959"   "6449091").PN.	USPAT	2004/03/03 14:54
-	23	peel\$4 same adhesive adj pad and (circuit adj board substrate)	USPAT; EPO; JPO	2004/03/03 15:00
-	4	peel\$4 same adhesive adj pad and (pry prying) and (circuit adj board substrate)	USPAT; EPO; JPO	2004/03/03 15:08
-	22	("4740977"   "4770505"   "4818881"   "4909612"   "4942076"   "5055652"   "5105307"   "5479540"   "5542018"   "5638391"   "5712728"   "5715080"   "5978135"   "6055102"   "6081638"   "6146025"   "6205274"   "6215295"   "6219470"   "6301279"   "6441959"   "6449091").PN.	USPAT	2004/03/03 15:07
-	5	(remov\$4 peel\$4) and (repair\$4 replac\$3 modif\$4) and adhesive adj pad and (pry prying) and (circuit adj board substrate)	USPAT; EPO; JPO	2004/03/03 15:34
-	8	("1186729"   "2655976"   "3830441"   "5387308"   "5454899"   "5551136"   "5891297"   "6004426").PN.	USPAT	2004/03/03 15:27
-	0	6221199.URPN.	USPAT	2004/03/03 15:28
-	3	crow adj bar and (remov\$4 peel\$4) and (repair\$4 replac\$3) and (pry prying) and (circuit adj board substrate)	USPAT; EPO; JPO	2004/03/03 15:29
-	25	crow adj bar and (remov\$4 peel\$4) and (circuit adj board substrate)	USPAT; EPO; JPO	2004/03/03 15:33
-	44	crow adj bar and (circuit adj board substrate)	USPAT; EPO; JPO	2004/03/03 15:33

-	207	(remov\$4 peel\$4) and (repair\$4 replac\$3 modif\$4) and adhesive and (pry prying) and (circuit adj board substrate)	USPAT; EPO; JPO	2004/03/03 16:17
-	3	("4637713"   "5311250"   "5422704").PN.	USPAT	2004/03/03 15:53
-	3	("4443098"   "4637713"   "4897966").PN.	USPAT	2004/03/03 15:54
-	2	5953107.URPN.	USPAT	2004/03/03 15:55
-	4	("4500895"   "4771295"   "5182581"   "5199470").PN.	USPAT	2004/03/03 15:58
-	24	5408256.URPN.	USPAT	2004/03/03 15:58
-	5	5326016.URPN.	USPAT	2004/03/03 16:03
-	1	"3210182".PN.	USPAT	2004/03/03 16:04
-	11	4059467.URPN.	USPAT	2004/03/03 16:16
-	36	(remov\$4 peel\$4) and (repair\$4 replac\$3 modif\$4) and adhesive and (pry prying) with tool and (circuit near2 board substrate)	USPAT; EPO; JPO	2004/03/03 16:19
-	46	(remov\$4 peel\$4) and adhesive and (pry prying) with tool and (circuit near2 board substrate)	USPAT; EPO; JPO	2004/03/03 16:24
-	8	("4325599"   "5315063"   "5564939"   "5586906"   "5609498"   "6091474"   "6283793"   "6319075").PN.	USPAT	2004/03/03 16:19
-	20	(remov\$4 peel\$4) and adhesive and (pry prying) with tool and 29/\$.ccls.	USPAT; EPO; JPO	2004/03/03 16:31
-	1	5448814.URPN.	USPAT	2004/03/03 16:25
-	17	("D013430"   "D013431"   "D029985"   "0061504"   "0167368"   "0284521"   "0496913"   "0583901"   "0605482"   "0611479"   "0729829"   "0896458"   "1072479"   "1611408"   "2049104"   "3175436"   "5079791").PN.	USPAT	2004/03/03 16:26
-	6	1611408.URPN.	USPAT	2004/03/03 16:26
-	8	(remov\$4 peel\$4) and adhesive and (pry prying) with tool and 174/\$.ccls.	USPAT; EPO; JPO	2004/03/03 16:33
-	8	("4325599"   "5315063"   "5564939"   "5586906"   "5609498"   "6091474"   "6283793"   "6319075").PN.	USPAT	2004/03/03 16:31
-	14	("4847146"   "5103375"   "5170326"   "5355280"   "5450286"   "5783862"   "5789815"   "5969945"   "5982630"   "5986886"   "5998738"   "6037658"   "6054198"   "6275381").PN.	USPAT	2004/03/03 16:33
-	11	(remov\$4 peel\$4) and adhesive and (pry prying) with tool and 156/\$.ccls.	USPAT; EPO; JPO	2004/03/03 16:35
-	176	(remov\$4 peel\$4) and adhesive and (pry prying) with tool and (rework\$4 repair\$4 replac\$4)	USPAT; EPO; JPO	2004/03/03 17:49
-	4	5850657.URPN.	USPAT	2004/03/03 16:42
-	16	("0180187"   "0912028"   "1055851"   "1261844"   "1434744"   "1779293"   "2496280"   "2593304"   "2674794"   "2828502"   "3091852"   "3155997"   "4524514"   "5009009"   "5020181"   "5455981").PN.	USPAT	2004/03/03 16:42
-	9	circuit with remov\$4 same (prying pry) and 29/\$.ccls.	USPAT; EPO; JPO	2004/03/03 17:59
-	1	5778720.URPN.	USPAT	2004/03/03 17:50

-	10	("2629584"   "3029502"   "3577848"   "3744758"   "4307510"   "4649618"   "5075945"   "5778720"   "5909074"   "5974646").PN.	USPAT	2004/03/03 17:51
-	11	("2844060"   "2852971"   "2957376"   "3105299"   "3564715"   "3579797"   "3678561"   "3736643"   "4189964"   "4509242"   "4922615").PN.	USPAT	2004/03/03 17:52
-	8	5152052.URPN.	USPAT	2004/03/03 17:54
-	7	5502887.URPN.	USPAT	2004/03/03 17:57
-	1	circuit with remov\$4 same (prying pry) and 359/\$.ccls.	USPAT; EPO; JPO	2004/03/03 18:01
-	17	circuit with remov\$4 same (prying pry) and 361/\$.ccls.	USPAT; EPO; JPO	2004/03/03 18:03
-	8	5726859.URPN.	USPAT	2004/03/03 18:02
-	7	("3335327"   "3885173"   "4252390"   "4327953"   "4560216"   "4692790"   "5398157").PN.	USPAT	2004/03/03 18:02
-	12	circuit with remov\$4 same (prying pry) and 174/\$.ccls.	USPAT; EPO; JPO	2004/03/03 18:04
-	4	circuit with remov\$4 same (prying pry) and 156/\$.ccls.	USPAT; EPO; JPO	2004/03/03 18:05
-	9	(chip ic) same remov\$4 same (prying pry) and 29/\$.ccls.	USPAT; EPO; JPO	2004/03/03 18:07
-	3	(chip ic) same extract\$4 same (prying pry) and 29/\$.ccls.	USPAT; EPO; JPO	2004/03/03 18:07
-	5	(chip ic) same extract\$4 same (prying pry)	USPAT; EPO; JPO	2004/03/03 18:08
-	25	(chip ic) same tool same (prying pry)	USPAT; EPO; JPO	2004/03/03 18:13
-	6	5495651.URPN.	USPAT	2004/03/03 18:09
-	16	(chip ic) same(board substrate) and tool same (prying pry) and adhesive	USPAT; EPO; JPO	2004/03/03 18:15
-	16	(chip ic) same (board substrate) and tool same (prying pry) and adhesive	USPAT; EPO; JPO	2004/03/03 18:16
-	63	(chip ic) same (board substrate) and (prying pry) and adhesive	USPAT; EPO; JPO	2004/03/03 18:16
-	38	adhesive same (board substrate) and (prying pry) and insert\$4 and (peel\$4 remov\$4 cut\$4) with adhesive	USPAT; EPO; JPO	2004/03/03 18:38
-	1052	156/344,584.ccls. and adhesive	USPAT; EPO; JPO	2004/03/04 10:01
-	590	156/344,584.ccls. and adhesive and (peel\$4 remov\$3 seperat\$3) and forc\$3	USPAT; EPO; JPO	2004/03/04 10:09
-	19	(156/344,584.ccls. and adhesive and (peel\$4 remov\$3 seperat\$3) and forc\$3) and (prying pry)	USPAT; EPO; JPO	2004/03/04 10:02
-	16	3986265.URPN.	USPAT	2004/03/04 10:08
-	23	156/344,584.ccls. and adhesive and (peel\$4 remov\$3 seperat\$3) and (prying pry)	USPAT; EPO; JPO	2004/03/04 10:13
-	24	156/344,584.ccls. and connect\$3 and (peel\$4 remov\$3 seperat\$3) and (prying pry)	USPAT; EPO; JPO	2004/03/04 10:15
-	2	156/\$.ccls. and solder\$3 with connect\$3 and (peel\$4 remov\$3 seperat\$3) and (prying pry)	USPAT; EPO; JPO	2004/03/04 10:17
-	25	29/\$.ccls. and solder\$3 with connect\$3 and (peel\$4 remov\$3 seperat\$3) and (prying pry)	USPAT; EPO; JPO	2004/03/04 10:24
-	23	3990863.URPN.	USPAT	2004/03/04 10:20
-	0	(solder\$3 with connect\$3 and (peel\$4 remov\$3 seperat\$3) with (prying pry)) and folk	USPAT; EPO; JPO	2004/03/04 10:25

-	80	solder\$3 with connect\$3 and (peel\$4 remov\$3 seperat\$3) with (prying pry)	USPAT; EPO; JPO	2004/03/04 10:43
-	83	solder\$3 with connect\$3 and (peel\$4 remov\$3 seperat\$3) same (prying pry) and insert\$4	USPAT; EPO; JPO	2004/03/04 10:48
-	23	4189199.URPN.	USPAT	2004/03/04 10:46
-	81	solder\$3 and (peel\$4 remov\$3 seperat\$3) same (prying pry) and insert\$4 same tool	USPAT; EPO; JPO	2004/03/04 10:53
-	4	solder\$3 same (chip ic) and (prying pry) same insert\$4 same tool	USPAT; EPO; JPO	2004/03/04 10:55
-	118	solder\$3 same (chip ic) and (prying pry remov\$3) same insert\$4 same tool	USPAT; EPO; JPO	2004/03/04 14:04
-	16	4034202.URPN.	USPAT	2004/03/04 10:59
-	4	("3230338"   "3673384"   "3804320"   "3895214").PN.	USPAT	2004/03/04 11:01
-	13	3895214.URPN.	USPAT	2004/03/04 11:01
-	13	3804320.URPN.	USPAT	2004/03/04 11:02
-	7	("2226194"   "3230338"   "3529760"   "3632036"   "3632972"   "3632973"   "3649809").PN.	USPAT	2004/03/04 11:03
-	20	3632973.URPN.	USPAT	2004/03/04 11:03
-	11	("3529760"   "3230338"   "2512426"   "1240138"   "2448182"   "1439593"   "2056256"   "0703638"   "3130286"   "2751485"   "3339059").PN.	USPAT	2004/03/04 11:05
-	372	29/758.ccls.	USPAT; EPO; JPO	2004/03/04 14:26
-	251	29/762.ccls.	USPAT; EPO; JPO	2004/03/04 14:35
-	385	29/764.ccls.	USPAT; EPO; JPO	2004/03/04 14:36
-	195	29/764.ccls. and (prying pry rais\$4 extract\$4 detach\$4)	USPAT; EPO; JPO	2004/03/04 14:46
-	389	29/\$.ccls. and (prying pry rais\$4 extract\$4 detach\$4) same (chip ic) and (tool lever leverage)	USPAT; EPO; JPO	2004/03/04 14:53
-	155	(29/\$.ccls. and (prying pry rais\$4 extract\$4 detach\$4) same (chip ic) and (tool lever leverage)) and solder\$4	USPAT; EPO; JPO	2004/03/04 14:48
-	219	adhesive and (prying pry rais\$4 extract\$4 detach\$4) same (chip ic) and (tool lever leverage) and solder with connect\$4	USPAT; EPO; JPO	2004/03/04 14:58
-	59	(adhesive and (prying pry rais\$4 extract\$4 detach\$4) same (chip ic) and (tool lever leverage) and solder with connect\$4) and optical	USPAT; EPO; JPO	2004/03/04 14:54
-	285	bonding and (prying pry rais\$4 extract\$4 detach\$4) same (chip ic) and (tool lever leverage) and solder with connect\$4	USPAT; EPO; JPO	2004/03/04 14:59
-	130	bonding and (prying pry rais\$4 extract\$4 detach\$4) same (chip ic) and (tool lever leverage) and solder with connect\$4 and insert\$4	USPAT; EPO; JPO	2004/03/04 15:03
-	19	(peeling peel) and (prying pry rais\$4 extract\$4 detach\$4) same (tool lever leverage) and solder with connect\$4 and insert\$4	USPAT; EPO; JPO	2004/03/04 15:43
-	1240	(prying pry rais\$4 extract\$4 detach\$4) same (tool lever leverage) and (adhesive solder) with (pad connect\$4) and (peel\$3 insert\$3)	USPAT; EPO; JPO	2004/03/04 15:56
-	772	((prying pry rais\$4 extract\$4 detach\$4) same (tool lever leverage) and (adhesive solder) with (pad connect\$4) and (peel\$3 insert\$3)) and (lead wire)	USPAT; EPO; JPO	2004/03/04 15:46

-	114	((prying pry rais\$4 extract\$4 detach\$4) same (tool lever leverage) and (adhesive solder) with (pad connect\$4) and (peel\$3 insert\$3)) and (lead wire)) and solder with heat\$3	USPAT; EPO; JPO	2004/03/04 15:55
-	179	(prying pry rais\$4 extract\$4 detach\$4) and (adhesive solder) adj pad and peel\$3	USPAT; EPO; JPO	2004/03/04 17:26
-	463	(prying pry extract\$4 detach\$4) and (adhesive solder) adj pad and (board substrate)	USPAT; EPO; JPO	2004/03/04 17:41
-	123	((prying pry extract\$4 detach\$4) and (adhesive solder) adj pad and (board substrate)) and tool	USPAT; EPO; JPO	2004/03/04 17:29
-	5	(prying pry extract\$4 detach\$4) and (adhesive solder) adj pad and (board substrate) and optic\$4 adj device	USPAT; EPO; JPO	2004/03/04 17:59
-	113	(prying pry extract\$4 detach\$4) and (adhesive solder) adj pad and (board substrate) and optical	USPAT; EPO; JPO	2004/03/04 18:04
-	923	(prying pry extract\$4 detach\$4) and (adhesive solder) with device and (board substrate) and optical	USPAT; EPO; JPO	2004/03/04 18:05
-	125	(prying pry extract\$4 detach\$4) and (adhesive solder) with device and (board substrate) and optical adj device	USPAT; EPO; JPO	2004/03/04 18:16
-	26	(prying pry) and (peel\$3 remov\$4) with (adhesive solder) and (lead wire pin) and (board substrate) and (ic chip packag\$3) same device	USPAT; EPO; JPO	2004/03/04 18:36
-	36	("3097360"   "3545606"   "3892313"   "4074342"   "4099615"   "4373778"   "4442938"   "4514784"   "4595794"   "4620757"   "4645278"   "4645287"   "4678250"   "4693528"   "4750092"   "4838801"   "4939624"   "5034855"   "5135890"   "5144412"   "5145386"   "5168432"   "5174764"   "5184285"   "5188536"   "5199884"   "5215472"   "5242311"   "5277597"   "5336118"   "5373984"   "5400220"   "5452183"   "5515241"   "5537295"   "5538433").PN.	USPAT	2004/03/04 18:23
-	1	5287617.pn.	USPAT; EPO; JPO	2004/03/04 18:24
-	778	peel\$3 with (adhesive solder) and (lead wire pin) and (board substrate) and (ic chip packag\$3) same device	USPAT; EPO; JPO	2004/03/04 18:37
-	420	peel\$3 with (adhesive solder) with (layer pad film) and (lead wire pin) and (board substrate) and (ic chip packag\$3) same device	USPAT; EPO; JPO	2004/03/04 18:44
-	99	(peel\$3 with (adhesive solder) with (layer pad film) and (lead wire pin) and (board substrate) and (ic chip packag\$3) same device) and optical	USPAT; EPO; JPO	2004/03/04 18:38
-	5	peel\$3 with (adhesive solder) with (layer pad film) and (lead wire pin) and (board substrate) and (ic chip packag\$3) same device and (prying pry)	USPAT; EPO; JPO	2004/03/04 18:45
-	5	peel\$3 with (adhesive solder) with (layer pad film) and (lead wire pin) and (ic chip packag\$3) same device and (prying pry lever leverag\$4) same tool	USPAT; EPO; JPO	2004/03/04 18:46
-	20	peel\$3 with (adhesive solder) with (layer pad film) and (lead wire pin) and (prying pry lever leverag\$4) same tool	USPAT; EPO; JPO	2004/03/04 18:46